

CLAIMS

1. An electronic component mounting method for mounting the electronic component on a substrate by soldering a connection terminal of the electronic component to an electrode provided on the substrate, comprising an adhesive
5 supplying step of supplying a thermosetting adhesive mixing solder particles to the substrate, a component mounting step of mounting the electronic component on the substrate after the adhesive supplying step, and a heating step of heating the substrate after the component mounting step,

10 wherein the adhesive supplying step is characterized by supplying the adhesive to the electrode, and also supplying the adhesive to an adhesion reinforcing portion determined outside of the electrode on the substrate,

the component mounting step is characterized by fitting the connection terminal to the adhesive supplied on the electrode, and also fitting the electronic component to the adhesive supplied in the adhesion reinforcing portion, and

15 the heating step is characterized by forming a solder junction by bonding the connection terminal and electrode by fusing the solder particles in the adhesive supplied to the electrode, and also forming an adhesion reinforced part for fixing the electronic component to the substrate by heating and curing the adhesive by sealing the inside of the adhesive with solder part by fusing and solidifying of solder
20 particles contained in the adhesive supplied in the adhesion reinforcing portion.

2. The electronic component mounting method of claim 1, wherein the adhesion reinforcing portion is formed on the surface of the substrate, and partly overlaps with the plural electrodes, and the portion other than the electrodes is set on a concave resist film, and the solder part is held in the concave portion.

25 3. The electronic component mounting method of claim 1, wherein the

adhesion reinforcing portion is a position for covering the reinforcing electrode provided in other portion than the electrodes on the substrate, and the adhesion reinforced part is formed as the solder particles in the adhesive supplied in the reinforcing electrode are fused to cover the solder part bonded on the reinforcing electrode, and the adhesive is thermally cured to bond the electronic component to the substrate.

4. An electronic component mounting structure for mounting an electronic component having a connection terminal on a substrate with an electrode by a thermosetting adhesive mixing solder particles, comprising:

a soldering unit of bonding the electrode and the connection terminal formed by fusing and solidifying of the solder particles in the adhesive supplied in the electrode, and

an adhesion reinforcing unit for fixing the electronic component to the substrate by heating and curing of adhesive, by sealing the inside of adhesive with a solder part formed by fusing and solidifying of the solder particles in the adhesive, being formed in the adhesion reinforcing portion separated from the electrode portion on the substrate.

5. The electronic component mounting structure of claim 4, wherein the adhesion reinforcing portion is formed on the surface of the substrate, and partly overlaps with the plural electrodes, and the portion separated from the electrodes is set on a concave resist film, and the solder part is held in the concave portion.

6. The electronic component mounting structure of claim 4, wherein the adhesion reinforcing portion is a position for covering the reinforcing electrode provided in a portion separated from the electrodes on the substrate, and the adhesion reinforced part is formed as the solder particles in the adhesive supplied in

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the reinforcing electrode are fused to cover the solder part bonded on the reinforcing electrode, and the adhesive is thermally cured to bond the electronic component to the substrate.